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October 2014

FDMS8558S(PCN)

N-Channel PowerTrench® SyncFETTM

25 V, 90 A, 1.5 mΩ

Features

- Dual CoolTM PQFN package
- Max $r_{DS(on)}$ = 1.5 m Ω at V_{GS} = 10 V, I_D = 33 A
- Max $r_{DS(on)} = 1.7 \text{ m}\Omega$ at $V_{GS} = 4.5 \text{ V}$, $I_D = 31 \text{ A}$
- High performance technology for extremely low r_{DS(on)}
- SyncFETTM Schottky Body Diode
- RoHS Compliant

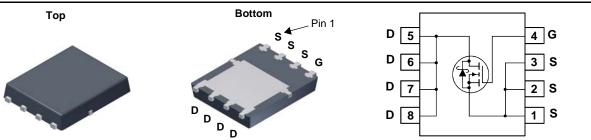


General Description

This N-Channel SyncFETTM is produced using Fairchild Semiconductor's advanced PowerTrench[®] process. Advancements in both silicon and package technologies have been combined to offer the lowest r_{DS(on)} while maintaining excellent switching performance by extremely low Junction-to-Ambient thermal resistance. This device has the added benefit of an efficient monolithic Schottky body diode.

Applications

- Synchronous Rectifier for DC/DC Converters
- Telecom Secondary Side Rectification
- High End Server/Workstation Vcore Low Side



MOSFET Maximum Ratings TA = 25°C unless otherwise noted

Power 56

Symbol	Parameter			Ratings	Units
V _{DS}	Drain to Source Voltage			25	V
V _{GS}	Gate to Source Voltage			12	V
	Drain Current -Continuous (Package limited)	T _C = 25 °C		90	
I _D	-Continuous	T _A = 25 °C	(Note 1a)	33	Α
	-Pulsed			140	
E _{AS}	Single Pulse Avalanche Energy		(Note 3)	145	mJ
D	Power Dissipation	T _C = 25 °C		78	W
P_{D}	Power Dissipation	T _A = 25 °C	(Note 1a)	2.5	VV
T _J , T _{STG}	Operating and Storage Junction Temperature Range			-55 to +150	°C

Thermal Characteristics

$R_{\theta JC}$	Thermal Resistance, Junction to Case	T _C = 25 °C		1.6	
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	T _A = 25 °C	(Note 1a)	50	°C/W

Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
09OD	FDMS8558S	Power 56	13"	12 mm	3000 units

Electrical Characteristics T_J = 25 °C unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Тур	Max	Units
Off Chara	acteristics					
BV _{DSS}	Drain to Source Breakdown Voltage	$I_D = 1 \text{ mA}, V_{GS} = 0 \text{ V}$	25			V
$\frac{\Delta BV_{DSS}}{\Delta T_{J}}$	Breakdown Voltage Temperature Coefficient	I _D = 10 mA, referenced to 25 °C		24		mV/°C
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 20 V, V _{GS} = 0 V			500	μΑ
I _{GSS}	Gate to Source Leakage Current	V _{GS} = +12 V/-8 V, V _{DS} = 0 V			±100	nA

On Characteristics

V _{GS(th)}	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}$, $I_D = 1 \text{ mA}$	1.1	1.4	2.2	V
$\Delta V_{GS(th)} \over \Delta T_J$	Gate to Source Threshold Voltage Temperature Coefficient	I _D = 10 mA, referenced to 25 °C		-3		mV/°C
r _{DS(on)}	Static Drain to Source On Resistance	$V_{GS} = 10 \text{ V}, I_D = 33 \text{ A}$		1.1	1.5	mΩ
		$V_{GS} = 4.5 \text{ V}, I_D = 31 \text{ A}$		1.3	1.7	
		$V_{GS} = 10 \text{ V}, I_D = 33 \text{ A}, T_J = 125 \text{ °C}$		1.6	2.1	
9 _{FS}	Forward Transconductance	$V_{DS} = 5 \text{ V}, I_{D} = 33 \text{ A}$		317		S

Dynamic Characteristics

C _{iss}	Input Capacitance	V 42.V.V 0.V	5118	pF
Coss	Output Capacitance	$V_{DS} = 13 \text{ V}, V_{GS} = 0 \text{ V},$ $f = 1 \text{ MHz}$	1508	pF
C _{rss}	Reverse Transfer Capacitance	1 - 1 1011 12	195	pF
R_a	Gate Resistance		0.9	Ω

Switching Characteristics

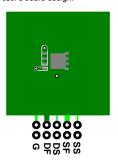
t _{d(on)}	Turn-On Delay Time		14	ns
t _r	Rise Time	V _{DD} = 13 V, I _D = 33 A,	8	ns
t _{d(off)}	Turn-Off Delay Time	$V_{GS} = 10 \text{ V}, R_{GEN} = 6 \Omega$	51	ns
t _f	Fall Time		7	ns
Q_q	Total Gate Charge	V _{GS} = 0 V to 10 V	81	nC
Q_q	Total Gate Charge	$V_{GS} = 0 \text{ V to } 4.5 \text{ V}$ $V_{DD} = 13 \text{ V}$	38	nC
Q_{gs}	Gate to Source Gate Charge	I _D = 33 A	10	nC
Q_{gd}	Gate to Drain "Miller" Charge		9.7	nC

Drain-Source Diode Characteristics

V _{SD}	Source to Drain Diode Forward Voltage	$V_{GS} = 0 \text{ V}, I_S = 2 \text{ A}$ (Note 2)	0.6	0.8	V
	Source to Drain blode Forward voltage	$V_{GS} = 0 \text{ V}, I_S = 33 \text{ A}$ (Note 2)	0.8	1.2	
t _{rr}	Reverse Recovery Time	-I _F = 33 A, di/dt = 300 A/μs	35		ns
Q _{rr}	Reverse Recovery Charge	- I _F = 33 A, α/αι = 300 A/μs	49		nC

NOTES

^{1.} R_{0JA} is determined with the device mounted on a FR-4 board using a specified pad of 2 oz copper as shown below. R_{0JC} is guaranteed by design while R_{0CA} is determined by the user's board design.



a) 50 °C/W when mounted on a 1 in² pad of 2 oz copper



b) 125 °C/W when mounted on a minimum pad of 2 oz copper.

^{2.} Pulse Test: Pulse Width < 300 $\mu s,$ Duty cycle < 2.0%.

^{3.} E_{AS} of 145 mJ is based on starting T_J = 25 °C, L = 0.9 mH, I_{AS} = 18 A, V_{DD} = 23 V, V_{GS} = 10 V. 100% test at L = 0.1 mH, I_{AS} = 39 A.

Typical Characteristics $T_J = 25$ °C unless otherwise noted

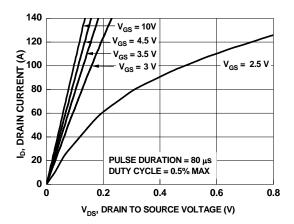


Figure 1. On Region Characteristics

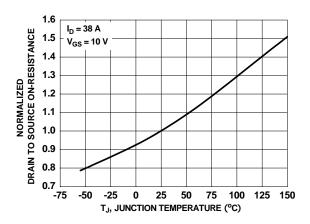


Figure 3. Normalized On Resistance vs Junction Temperature

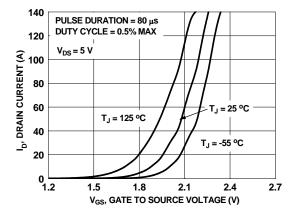


Figure 5. Transfer Characteristics

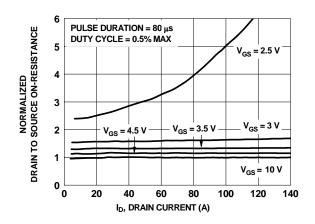


Figure 2. Normalized On-Resistance vs Drain Current and Gate Voltage

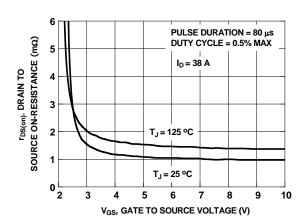


Figure 4. On-Resistance vs Gate to Source Voltage

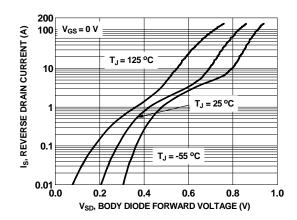


Figure 6. Source to Drain Diode Forward Voltage vs Source Current

Typical Characteristics $T_J = 25$ °C unless otherwise noted

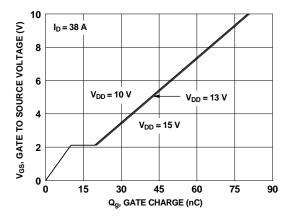


Figure 7. Gate Charge Characteristics

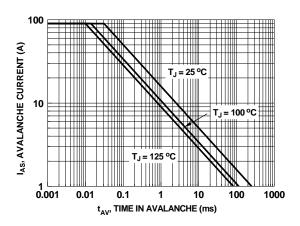


Figure 9. Unclamped Inductive Switching Capability

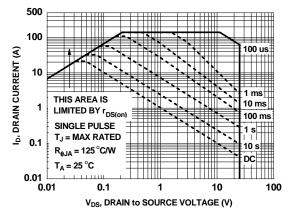


Figure 11. Forward Bias Safe Operating Area

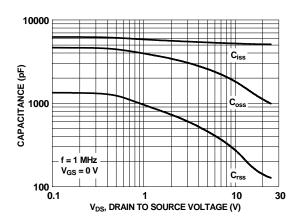


Figure 8. Capacitance vs Drain to Source Voltage

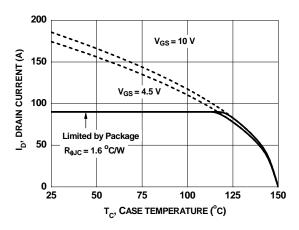


Figure 10. Maximum Continuous Drain Current vs Ambient Temperature

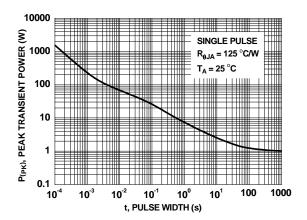


Figure 12. Single Pulse Maximum Power Dissipation

Typical Characteristics T_J = 25 °C unless otherwise noted

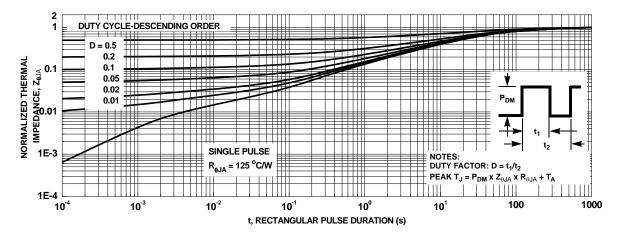


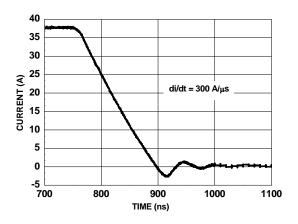
Figure 13. Junction-to-Ambient Transient Thermal Response Curve

Typical Characteristics (continued)

SyncFETTM Schottky body diode Characteristics

Fairchild's SyncFETTM process embeds a Schottky diode in parallel with PowerTrench MOSFET. This diode exhibits similar characteristics to a discrete external Schottky diode in parallel with a MOSFET. Figure 14 shows the reverse recovery characteristic of the FDMS8558S.

Schottky barrier diodes exhibit significant leakage at high temperature and high reverse voltage. This will increase the power in the device.



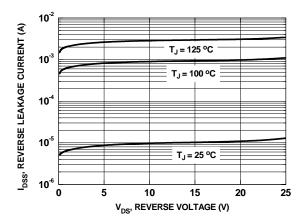


Figure 14. FDMS8558S SyncFETTM body diode reverse recovery characteristic

Figure 15. SyncFETTM body diode reverse leakage versus drain-source voltage



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